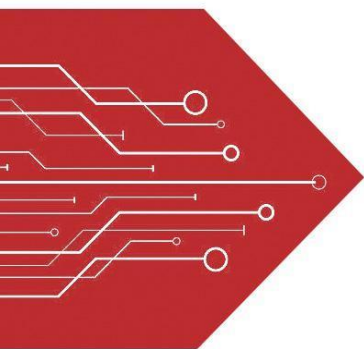


MSKSEMI

SEMICONDUCTOR



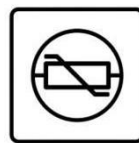
ESD



TVS



TSS



MOV



GDT

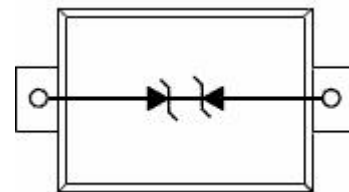


PLED

Product data sheet

Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies
- S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.



SOD-523

Features

- Small Body Outline Dimensions
- Low Body Height
- Peak Power up to 200 Watts @ 8 x 20 μ s Pulse
- Low Leakage current
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- IEC61000-4-4 Level 4 EFT Protection

Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. VF = 0.9V at IF = 10mA

P/N	V _{RWM} (V)	I _R (μ A) @ V _{RWM}	V _{BR} (V)@ I _T (Note 1)	I _T	V _C (V) @ I _{PP} =5 A*	V _C (V) @ Max I _{PP} *	I _{PP} (A)*	P _{PK} (W)*	C (pF)
	Max	Max	Min	mA	Typ	Max	Max	Max	Typ
MSESD5Z5.0C	5.0	1	5.6	1.0	11.6	18.6	9.4	174	25

Absolute Ratings (T_{amb}=25°C)

Symbol	Parameter	Value	Units
P _{pp}	Peak Pulse Power (t _p = 8/20 μ s)	200	W
T _L	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +155	°C
T _{op}	Operating Temperature Range	-40 to +125	°C
T _j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	± 15 ± 8	KV
	IEC61000-4-4 (EFT)	40	A
	ESD Voltage Per Human Body Model	16	KV

Electrical Parameter

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
I_T	Test Current
V_{BR}	Breakdown Voltage @ I_T

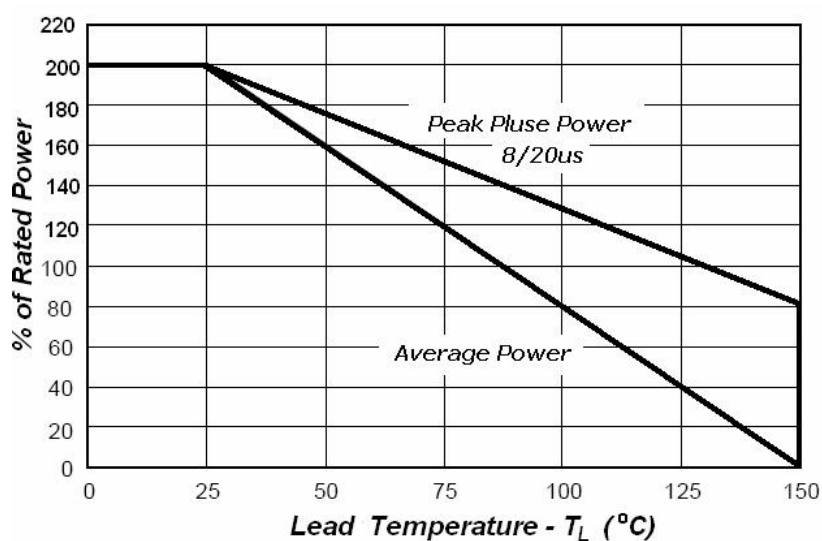
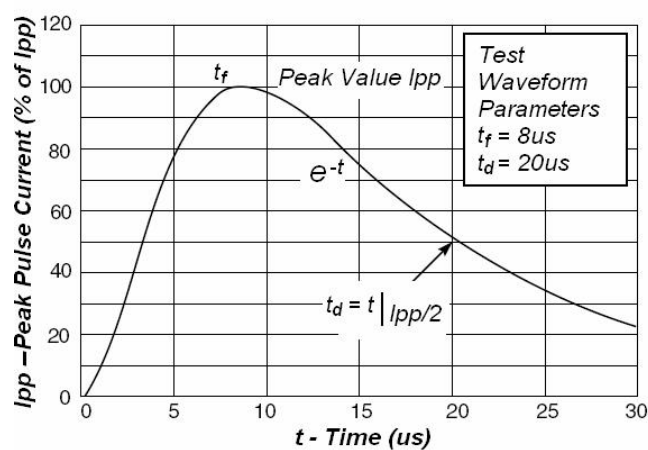
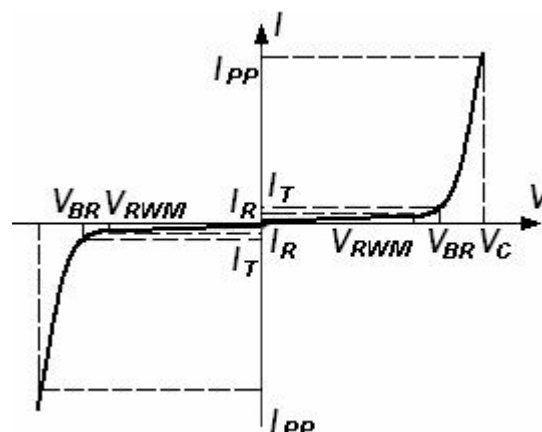
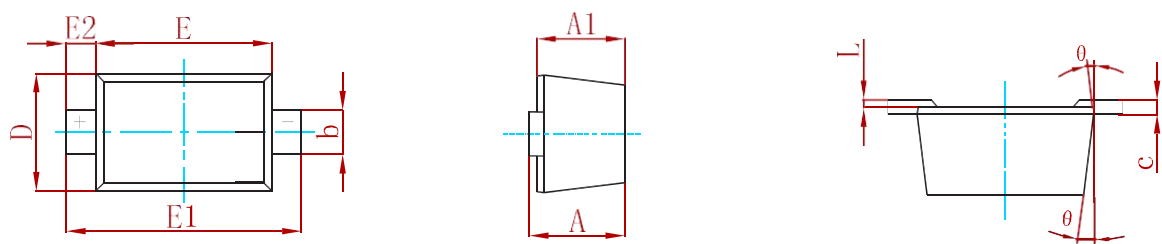


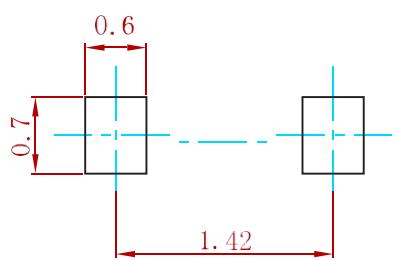
Fig2.Power Derating

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MSESD5Z5.0C	SOD-523	3000

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